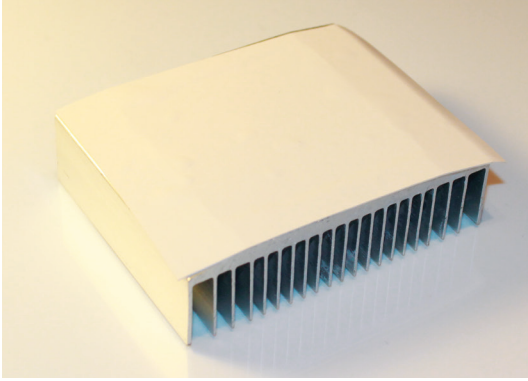


L37-3S

Thermal Conductive Pad



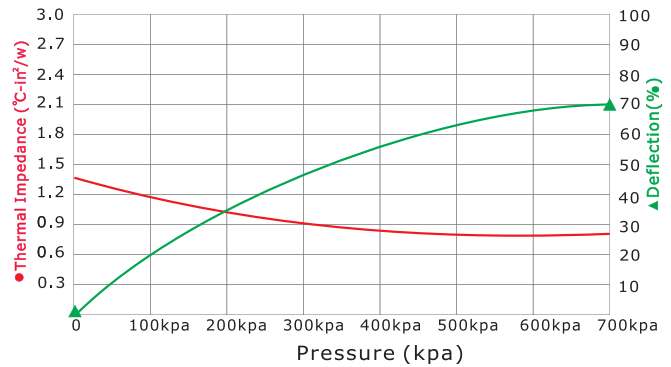
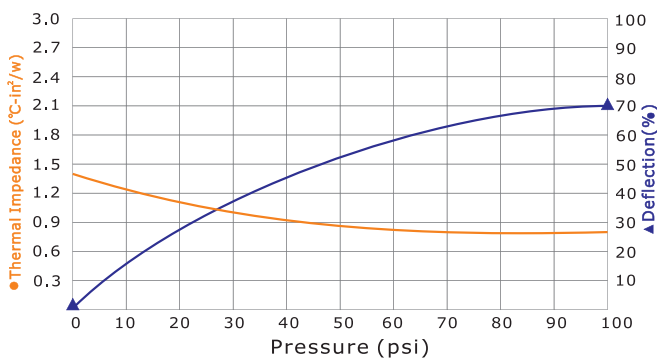
Features

- Good thermal conductivity
- Ultra soft and high compressibility
- Natural tack
- Easy to assemble
- Good insulator

Applications

- Electronic components: IC / CPU / MOS
- LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc....
- DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection

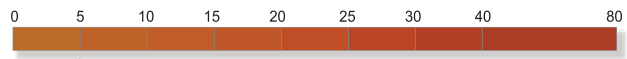
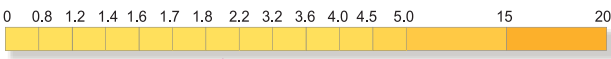


Properties

- REACH Compliant
- RoHS Compliant

Thermal Conductivity: 1.95 W/mK
(W/mK - Z Axis)

Hardness: 5 (Shore A)
(Shore A)



Testing sample thickness : 1.0 mm

In the thermal resistance vs pressure vs deflection charts L37-3S provides low thermal impedance. As the pressure increases the thermal impedance decreases. L37-3S provides good compliance and softness.

Property	L37-3S	Unit	Tolerance	Test Method
Colour	Light yellow	-	-	Visual
Thickness (Available thickness range)	0.5 - 20	mm	-	ASTM D374
	0.0197 - 0.787	inch	-	ASTM D374
Thermal Conductivity	1.95	W/mK	-	ASTM D5470
Flammability Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	>13	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	2.21	g/cm ³	±0.2	ASTM D792
Working Temperature	-40 to 200	°C	-	-
Volume Resistance	>10 ¹²	Ohm-cm	-	ASTM D257
Elongation	350	%	±0.2	ASTM D412
Tensile Strength	8	Kgf/cm ²	±5	ASTM D412
Standard Shape	-	Sheets 320-320mm	-	-
Hardness	5	Shore A	±3	ASTM D2240

Available with an adhesive backing

